Advanced Lithography and Wafer Bonding הזמנה לכנס

הנושאים הבאים יידונו על ידי מומחי החברה:

Lithography:

- + Light sources of the future
- + Edge Coating and Edge Stripping of wafer flats
- Imprinting of Optics on Wafer Level
- Nano Imprint Lithography
- New Nanoimprint materials with Superior Etching properties
- + MEMS
- + 3D Stacking Litho Considerations
- Laser Ablation and UV Scanning Lithography
- + High Precision Dispense and Spray Coating
- Improving proximity resolution using diffracting elements
- MEMS Packaging Fresnel Zone Plates for via formation in large exposure gaps

Wafer Bonding:

- Wafer Bonding Technologies for Wafer Level
 Packaging using high force bonding
- + Image sensors
- + MEMS
- + Temporary Bond-Debond Techniques
- + Automation of Permanent Wafer Bonding Processes

Guest Speaker Lecture (Allresist GmbH):

Novel Resins for Classic and e-Beam Lithography

SUSS MicroTec is a global supplier of production and RnD equipment for the semiconductor and related industries. Learn about the latest advances in the field:

- \checkmark New lithography techniques enable periodical structures on compound semiconductors
- ✓ Coating techniques at nanometer thickness accuracy
- ✓ 3D integration with temporary bonding/debonding
- ✓ Nano Imprint Lithography (NIL) opens ways to much more, such as wafer level camera production, photonic structures, and more.
- ✓ Vast improvements in MEMS manufacturing turned these devices into a production reality

Obiectives

Learn how to apply and use the different types of Coating, Bonding and Imprint techniques in the following markets: ELECTRONICS, HIGH PRECISION OPTICS, ADVANCED PACKAGING, MEMS, SENSORS, NANOTECHNOLOGY, OPTOELECTRONICS, POWER DEVICES, WIRELESS.



<u>הכנס ללא תשלום ויכלול כיבוד וארוחת צהריים.</u>

על מנת שנוכל להיערך מראש, נא אשרו בהקדם השתתפות באתר <u>www.picotech.co.il</u> ניתן להירשם גם באימייל: sussday2017@picotech.co.il

או לפנות לאורלי בטלפון: 03-635-6650

Bring your challenges with you and our experts will be happy to discuss them with you!

